

WHAT IS CLAIMED IS:

1. A motherboard comprising:  
a substrate;  
a interposer on said substrate;  
a DC-to-DC converter secured on said interposer;  
contacts located between the interposer and substrate.
2. The motherboard of claim 1, wherein the substrate contains power sockets.
3. The motherboard of claim 2, wherein the contact compresses into the power sockets to provide electrical connection.
4. The motherboard of claim 1, wherein said contacts are located underneath the interposer.
5. The motherboard of claim 1 wherein the contacts are located all around a die on the substrate.
6. The motherboard of claim 1, wherein the contacts are made of copper.